

AMENDMENTS TO THE CLAIMS

Listing Of Claims

Claims 1-20 (Canceled)

21. (currently amended) A method for testing a semiconductor component having a plurality of terminal contacts comprising:

providing a board comprising a plurality of contacts in electrical communication with test circuitry;

providing a substrate on the board;

providing a plurality of movable test contactors on the substrate comprising first contacts including first conductive polymer layers configured to electrically engage the terminal contacts and second contacts including second conductive polymer layers in electrical communication with the first contacts and configured to electrically engage the contacts;

placing the component on the substrate with the terminal contacts in electrical communication with the first contacts and the second contacts in electrical communication with the contacts; and

applying test signals through the test contactors and the terminal contacts to the component.

22. (previously presented) The method of claim 21 wherein the substrate comprises a plurality of grooves separating the contactors and forming flexible segments for the contactors.

23. (previously presented) The method of claim 21 further comprising applying a force to the component during the placing step.

24. (previously presented) The method of claim 21 wherein the substrate is configured to float on the board.

25. (previously presented) The method of claim 21 wherein the terminal contacts comprise an element selected from the group consisting of leads, bumps and pads.

26. (previously presented) The method of claim 21 wherein the placing step is performed using a test handler.

27. (previously presented) A method for testing a semiconductor component having a terminal contact comprising:

providing a board comprising at least one contact in electrical communication with test circuitry;

providing a substrate on the board comprising at least one contactor configured to simultaneously electrically engage the contact and the terminal contact, the contactor comprising a first conductive polymer layer on a first side of the substrate configured to electrically engage the terminal contact, and a second conductive polymer layer on a second opposing side of the substrate in electrical communication with the first conductive polymer layer configured to electrically engage the contact;

placing the component on the board with the first conductive polymer layer in electrical communication with the terminal contact and the second conductive polymer layer in electrical communication with the contact; and

applying test signals through the terminal contact, the contact, the second conductive polymer layer, and the first conductive polymer layer to the component.

28. (previously presented) The method of claim 27 wherein the substrate is configured to float in a Z-direction on the board,

29. (previously presented) The method of claim 27 wherein the substrate comprises grooves on either side of the contactor electrically isolating the contactor and forming a flexible segment on the substrate for the contactor.

30. (previously presented) The method of claim 27 wherein the terminal contact comprises an element selected from the group consisting of leads, bumps and pads.

31. (previously presented) The method of claim 27 wherein the component comprises an element selected from the group consisting of packages, BGA devices and modules.

32. (previously presented) A method for testing a semiconductor component having a plurality of terminal contacts comprising:

providing a board comprising a plurality of contacts in electrical communication with test circuitry;

providing a floating substrate on the board;

providing a plurality of test contactors on the substrate, each test contactor comprising a flexible segment on the substrate, a first conductive polymer layer on a first side of the flexible segment configured to electrically engage a terminal contact, and a second conductive polymer layer on a second opposing side of the flexible segment in electrical communication with the first conductive polymer layer and configured to electrically engage a contact on the board;

placing the component on the substrate with the terminal contacts in electrical communication with the test contactors; and

applying test signals through the test contactors and the terminal contacts to the component.

33. (previously presented) The method of claim 32 wherein the test contactors comprise an element selected from the group consisting of gold and platinum.

34. (previously presented) The method of claim 32 wherein the first conductive polymer layer and the second conductive polymer layer comprise an elastomeric base material and a plurality of conductive particles in the base material.

35. (previously presented) The method of claim 32 wherein the flexible segments allow the test contactors to move independently to accommodate dimensional variations in the terminal contacts.

36. (previously presented) The method of claim 32 wherein the terminal contacts comprise leads and the first conductive polymer layer comprises a plurality of conductive particles configured to penetrate a lead.

37. (previously presented) The method of claim 32 wherein the terminal contacts comprises bumps and the first conductive polymer layer comprises an indentation for engaging a bump.

38. (previously presented) The method of claim 32 wherein the terminal contacts comprise pads and the first conductive polymer layer comprises a bump for engaging a pad.

39. (previously presented) The method of claim 32 wherein the placing step is performed using a test handler.

40. (previously presented) The method of claim 32 wherein the substrate comprises an opening and the board comprises a pin for physically engaging the opening.

Claims 41-77 (Canceled)